

700~1000MHz Cellular & GSM900

Device Features

- Typical Isolation = 23 dB
- Typical Insertion Loss = 0.5 dB
- MSL 3 moisture rating
- RoHS2-compliant SOIC-8 Plastic Package With exposed back side ground pad

Product Description

BeRex's Divider BD09B is designed for Cellular & GSM band with low Insertion Loss and Isolation. This chip is fully passivated for enhanced performance and reliability and packaged in RoHS2-compliant with SOIC-8 surface mount package.

It can be used without back side ground soldering. (This may degrade the performance at the high frequency edge.)

Typical Performance¹

Parameter Min	Fypical	Max	Unit
Frequency Range 700		1000	MHz
Insertion Loss	0.5	0.8	dB
Isolation 15	23		dB
IRL(S11)	-20	-15	dB
ORL(S22/S33)	-23	-15	dB
Amplitude Balance	0.05	0.2	dB
Phase Balance	0.2	0.5	deg

- *All specifications apply to the following test conditions,
- 1. Device performance _ measured on BeRex E/B at 25°C, 50ohm system.
- 2. Insection Loss: Above 3.0dB.
- 3. Back side ground _ soldered.

Applications

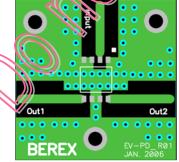
- Base station Infrastructure
- Commercial/Industrial/Military wirelessys

Absolute Maximum Ratings

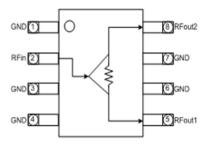
Parameter	Rating
Input Power	1W CW dBm
Storage Temperature	-55 to +155°C
Operating Temperature	-40 to +85°C

Operation of this device above any of these parameters may result in permanent damage.

Evaluation Board Drawing



Function Block Diagram



Pins 1,3,4,6 and 7 must be DC and RF grounded.



700~1000MHz Cellular & GSM900

Typical Test Data

With Back Side Ground Soldering

Parameters	Unit	Cellular & GSM900						
Frequency Range	MHz	700	750	800	850	900	950	1000
Insertion Loss	dB	0.48	0.50	0.49	0.52	0.54	0.59	0.65
Isolation	dB	16.7	20.6	25.4	27.0	22.9	19.5	17.1
IRL(S11)	dB	-19.5	-21.8	-23.8	-24.2	-02.0	19.2	-16.8
ORL(S22,S33)	dB	-21.9	-25.4	-28.1	-262	-22.8	-20.0	-17.9
Phase Diff.	deg	0.1	0.2	0.2	0.2	0,3	0.4	0.4
Amplitude Balance	dB	0.00	0.00	0.01	1803	0.02	0.01	0.01

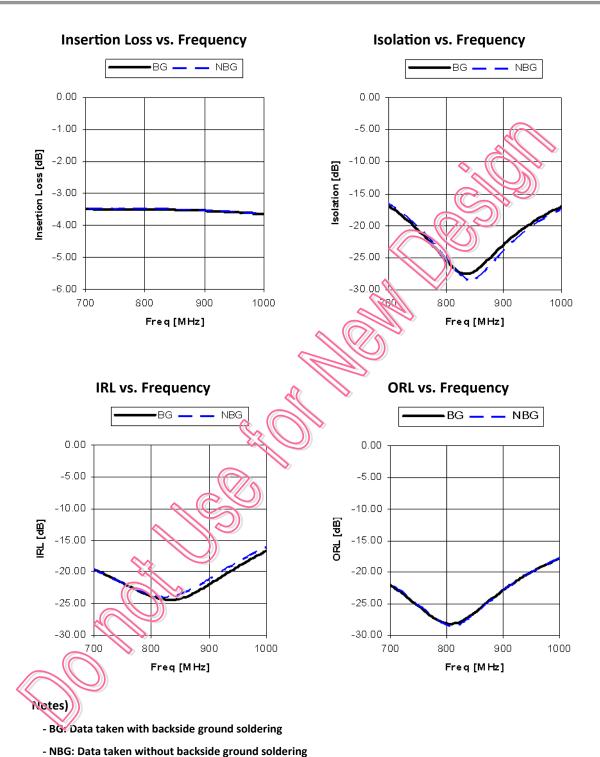
Without Back Side Ground Soldering

Parameters	Unit	Cellular & GSM900						
Frequency Range	MHz	700	750	800	850	900	950	1000
Insertion Loss	dB	0.46	0.49	0.48	0.49	0.52	0.58	0.64
Isolation	dB	16.4	20.2	25.1	28.3	23.9	20.1	17.5
IRL(S11)	dB	-19-5	-21.8	-23.8	-23.5	-21.2	-18.5	-16.1
ORL(S22,S33)	dB	21.8	-25.3	-28.3	-26.5	-22.9	-20.1	-17.9
Phase Diff.	deg	8.4	0.5	0.6	0.5	0.7	0.6	0.6
Amplitude Balance	dB	0.01	0.02	0.02	0.02	0.02	0.03	0.03





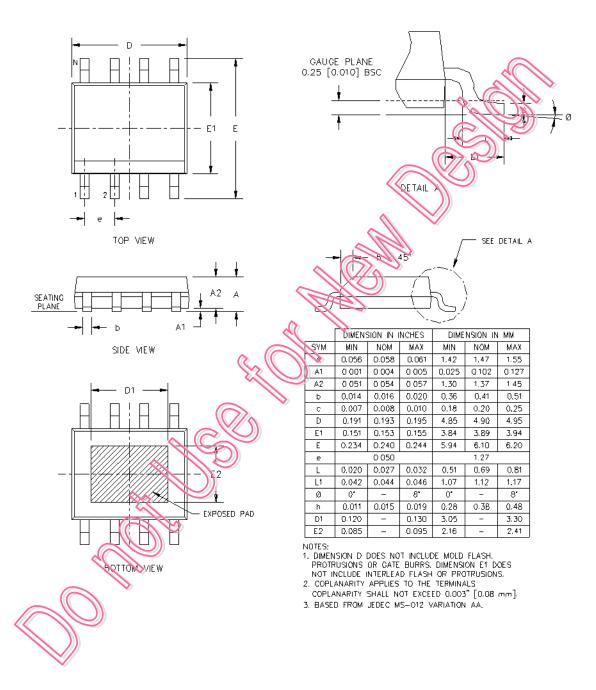
700~1000MHz Cellular & GSM900





700~1000MHz Cellular & GSM900

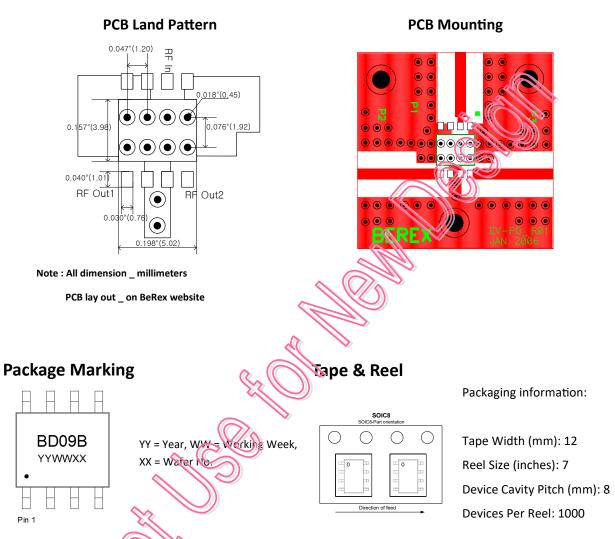
Package Outline Drawing





700~1000MHz Cellular & GSM900

Suggested PCB Land Pattern and PAD Layout



Lead plating finish



Pin 1

100% Tin Matte finish

(All BeRex products undergoes a 1 hour, 150 degree C, Anneal bake to eliminate thin whisker growth concerns.)





700~1000MHz Cellular & GSM900

MSL / ESD Rating

MSL Rating: Level 3 at +260°C convection reflow

Standard: JEDEC Standard J-STD-020



Caution: ESD Sensitive
Appropriate precautions in handling, packaging
and testing devices must be observed.

Proper ESD procedures should be followed when hading this device.

RoHS Compliance

This part is compliant with Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) Directive 2011/65/EU as amended by Directive 2015/863/EU. This product also is compliant with a concentration of the Substances of Very High Concern (SVHC) can-

didate list which are contained in a quantity of less than 0.1%(w/w) in each components of a product and/or its packaging placed on the European Community market by the BeRex and Suppliers.



